

## The first edition of the third decade of the TIE event

In less than four months, short after the Easter Holiday, between 25<sup>th</sup> and 28<sup>th</sup> of April, it will start the XXI edition of the TIE event. The host of the event will be “Lucian Blaga” University of Sibiu ([www.uslb.ro](http://www.uslb.ro)), located in the Sibiu, one of the most picturesque cities of Romania. Actually Sibiu, together with Luxembourg, was, in 2007 the cultural capitals of Europe.

TIE event is supported by IEEE CPMT Hu&Ro Joint Chapter and by the Electronic Packaging Education Training and Research University Network – EPETRUN-developed in our region. With the participation of the Budapest University of Technology and Economics, coordinator Prof. Zsolt Illyefalvi-Vitez, starting with the 2009 edition, TIE has extended beyond the Romanian borders and is now an important event of the IEEE CPMT Hu&Ro Joint Chapter. This year the local organizing committee is chaired by Prof. Dr. Ioan P. Mihi (Computer and Electrical Engineering Department).



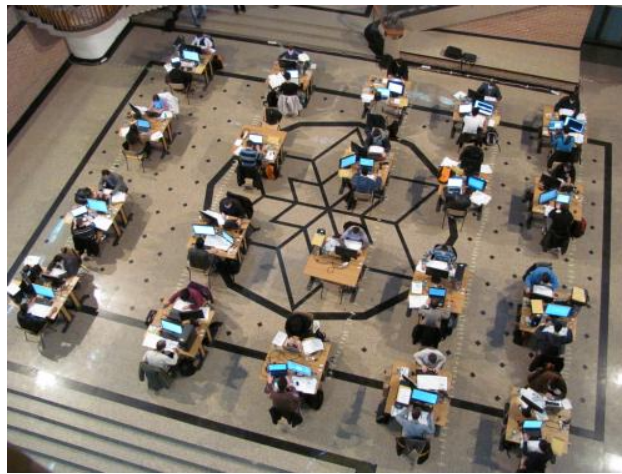
*TIE coordinators (left to right): Prof. Dan Pitiță, IEEE-CPMT Hu&Ro Joint Chapter Chair, Technical University of Cluj-Napoca, Romania, Prof. Zsolt Illyefalvi-Vitez, IEEE-CPMT Hu&Ro Joint Chapter, Vice-chair, Budapest University of Technology and Economics, Hungary, and Prof. Paul Svasta, Advisor IEEE-CPMT Student Branch Chapter of "Politehnica" University of Bucharest, Romania with the Winner's Cups (one of the cups is given to the winner's university and is transmissible, the other goes to the winner).*

The aim of the TIE event is to help in the process of training young professionals, enable them to acquire skills and competences and become familiar with the requirements of the industry during their academic training. The fact that the contest has an international prestige means that all students, who reach the final stage, have been involved in a challenging project which surely represents a good starting point for their future professional life.

The topics of the contest cover all fields of PCB CAD from parts and footprint creation, to designing schematic projects and developing optimal layouts according to various industrial restrictions (with special placement, routing and finishing issues), ending with post-processing output files. The Technical Committee (technical manager Assoc. Prof. Norocel Codreanu) develops the up-to-date topics and assures also, with the help of Organizing Committee, that the contest takes place in a fair-play climate. All information is available online on the [www.tie.ro](http://www.tie.ro) website, where one can find the regulations as well as examples from the past editions that give a good

overview of the proposed design topics, carefully reviewed by the Steering and Technical Committee.

The Industrial Advisor Committee, chaired by Cosmin Moisa, Continental Automotive SRL Timisoara, participates in the writing of subjects as well as in the evaluation and sets the line above which are located the people with real knowledge in the field of PCB design, those students being recommended as PCB designers. Because of the interaction with the industry the best students are certified as PCB designers, a proof that for many of them proved helpful in their future career as engineers. During the years, representatives from company such as Continental Timisoara and Sibiu, Siemens, IBL, Cadence, Altium, etc. have been invited at the TIE workshops and their presence has been highly motivational for the students as well as for the organizers



TIE competition in process

The first three ranked students received a one year scholarship. Other prizes were awarded by CAD software providers to high ranking students who used their software. Also the first 12 competitors have received from the IAC (Industrial Advisor Committee) the „PCB Designer” degree, as recognition of their high level of knowledge in the field of CAD for development of electronic modules and assemblies.



Participants to TIE 2011